

LNPTM STAT-KONTM COMPOUND WEF32ISP

REGION EUROPE

DESCRIPTION

LNP * STAT-KON* WEF32ISP is a compound based on Polybutylene Terephalate resin containing Glass Fiber and Carbon Fiber. Added features include High Impact, Heat Stabilized and Electrically Conductive.

TYPICAL PROPERTY VALUES

Revision 20181231

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL			
Tensile Stress, break, 5 mm/min	101	MPa	ISO 527
Tensile Strain, break, 5 mm/min	4	%	ISO 527
Flexural Stress, break, 2 mm/min	152	MPa	ISO 178
Flexural Modulus, 2 mm/min	7800	MPa	ISO 178
IMPACT			
Izod Impact, unnotched 80*10*4 +23°C	65	kJ/m²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	17	kJ/m²	ISO 180/1A
THERMAL			
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	191	°C	ISO 75/Af
PHYSICAL			
Mold Shrinkage, flow	0.15	%	SABIC method
Density	1.36	g/cm³	ISO 1183
ELECTRICAL			
Surface Resistivity	1.E+03 – 1.E+05	Ohm	ASTM D 257
INJECTION MOLDING			
Drying Temperature	120	°C	
Drying Time	4	hrs	
Maximum Moisture Content	0.05	%	
Melt Temperature	240 – 265	°C	
Front - Zone 3 Temperature	260 – 270	°C	
Middle - Zone 2 Temperature	245 – 255	°C	
Rear - Zone 1 Temperature	220 – 230	°C	
Mold Temperature	80 – 100	°C	
	0.2 - 0.3	MPa	
Back Pressure	0.2 - 0.3	IVII a	

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